



SXM330

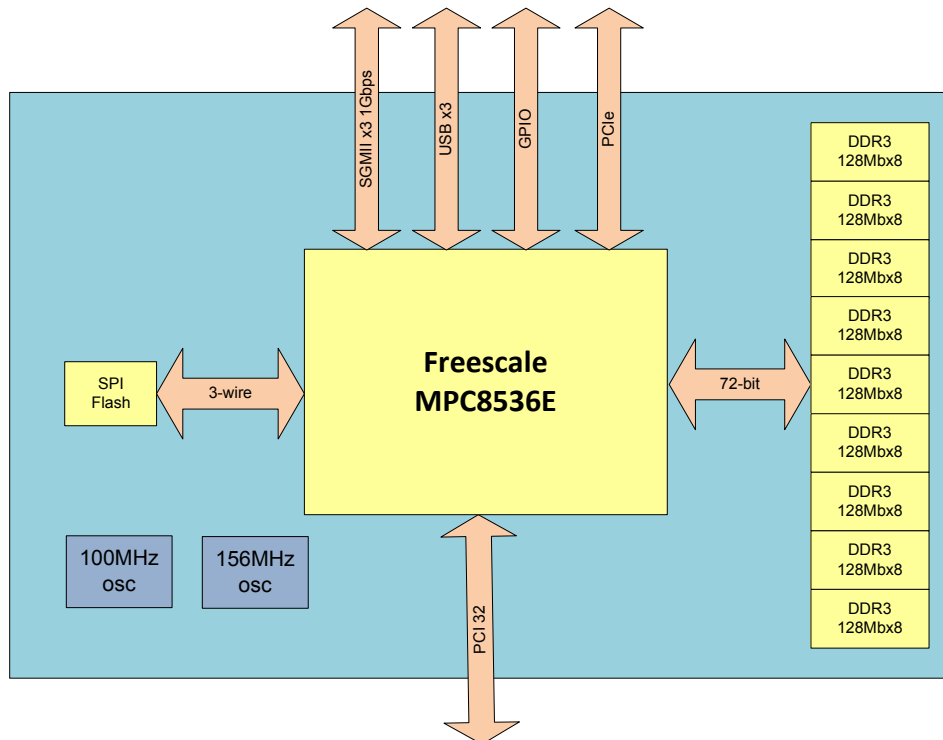
Embedded Processor Module

INTEGRATED PROCESSOR COMPUTING MODULE

The SXM330 is an off-the-shelf high performance low power embedded processor computing module with Freescale processor, FPGA accelerator and low power memory. The module utilizes siXis' unique Silicon Circuit Board (SiCB) technology. This technology uses a combination of bare-die and packaged components to achieve superior size, weight, and power characteristics in an industry-standard package allowing it to be processed using commercial methods.

Key Features

- Freescale PowerQUICC III MPC8536E
- DDR3 memory @533 MHz w/ ECC
- On-board bypass capacitors
- On-board oscillators
- 3.5 mm package height



SXM330 Technical Specifications

Compute FPGA:

- Freescale PowerQUICC III MPC8536E
- 2 Gbit DDR3 64M x 32 bits
- SPI Flash

Mechanical:

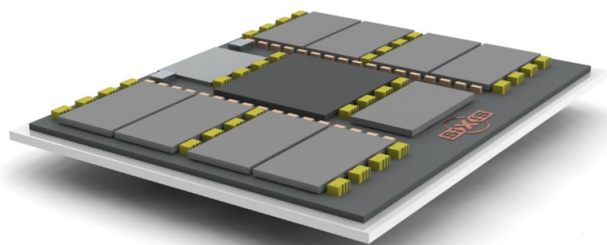
40 X 40 X 3.5 mm

I/O:

- Config and JTAG
- General purpose I/O
- SGMII
- USB
- PCIe

Required Input Power:

TBD



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